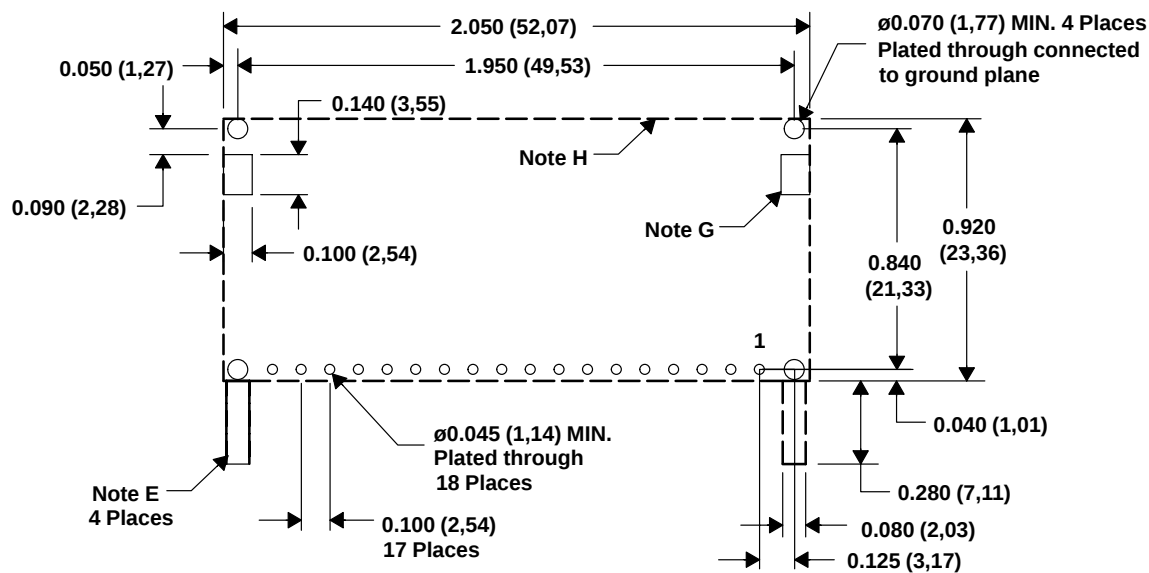
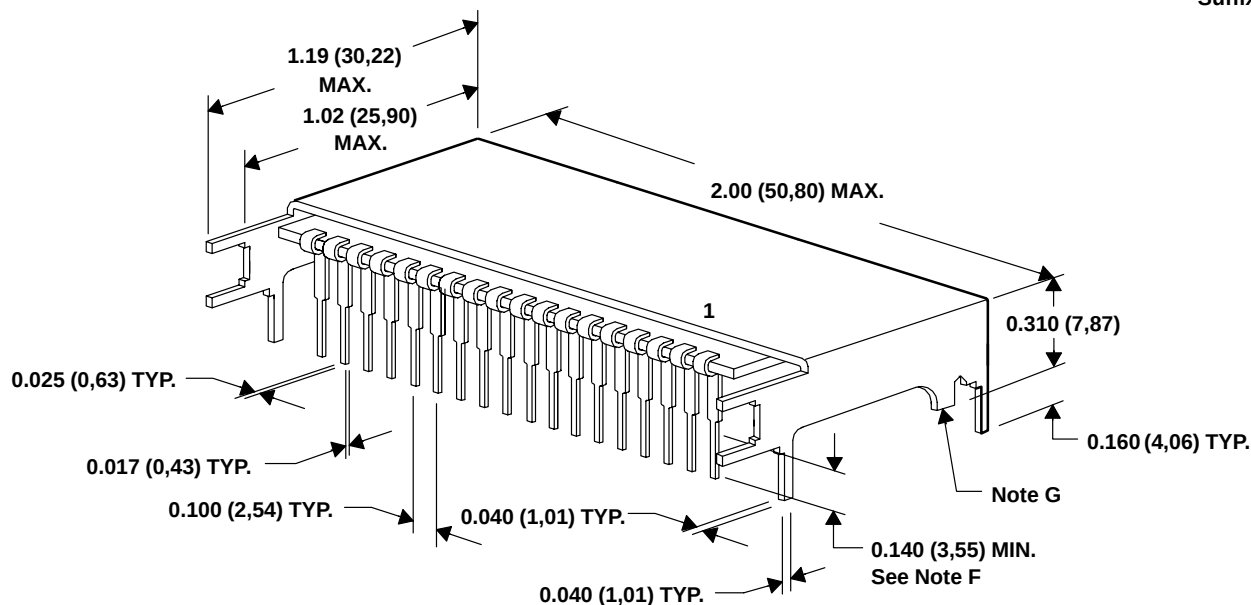


EPQ (R-MSIP-T18)

METAL SINGLE-IN-LINE MODULE

Suffix A



PC LAYOUT

4204497/A 06/02

- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 E. Recommended mechanical keep out area.

- F. Electrical pin length mounted on circuit board from seating plane to pin end.
 G. The case may be electrically connect to power ground plane.
 H. Case outline reference.

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